



The following material specifications are available:

Mark	Materials	Dimension	Surface qualities	Material No.
A	Oxygenfree copper SE-Cu58 (C103)	0.010 x 250 mm	Plain – lamination quality (standard degreased)	145547
B	Oxygenfree copper SE-Cu58 (C103)	0.010 x 250 mm	Plain – electrolytically degreased (enhanced degreasing)	145546
A1	Oxygenfree copper SE-Cu58 (C103)	0.018 x 250 mm	Plain – lamination quality (standard degreased)	145549
D	High Tensile Copper CuMgAgP (ASTM: C15500)	0.010 x 250 mm	Plain – lamination quality (standard degreased)	148050
E	High Tensile Copper CuMgAgP (ASTM: C15500)	0.010 x 250 mm	Plain – electrolytically degreased (enhanced degreasing)	148051
H	High Tensile Copper CuFe2P (ASTM: C19400)	0.010 x 250 mm	Plain – lamination quality (standard degreased)	153085
J	High Tensile Copper CuNi3Si (ASTM: C7025)	0.010 x 250 mm	Plain – lamination quality (standard degreased)	153143 coming soon
	High Tensile Copper CuNi3Si ASTM: C7025)	0.010 x 180 mm	Plain – lamination quality (standard degreased)	154415 temporarily available only
K	High Tensile Copper CuNi3Si (ASTM: C7025)	0.010 x 250 mm	Plain – electrolytically degreased (enhanced degreasing)	153144
F	Nickel 99.6 (N201)	0.011 x 250 mm	Plain – lamination quality (standard degreased)	148380
G	Nickel 99.6 (N201)	0.011 x 250 mm	Plain – electrolytically degreased (enhanced degreasing)	148389

RELATED PRODUCTS

Please consider also our material for bipolar electrode application and tab ribbon:

- **Aluminum Copper-Clad material** used for tab ribbon and bipolar electrode application and
- **Tab Ribbon** made from Copper, Silver, Nickel and their alloys

For further information please visit our website: www.schlenk.com or contact our Area Sales Manager or your local representative. E-Mail contact: battery@schlenk.com